

What is claimed is:

- 1           1. An LED lamp, comprising:  
2           a package; and  
3           a plurality of light emitting elements that are  
4           electrically connected to a plurality of electrode plates  
5           provided in the package and that are sealed with transparent  
6           material;  
7           wherein a red light emitting element of the plurality of  
8           light emitting elements is wire bonded along the longitudinal  
9           direction of the package, a green light emitting element and  
10          a blue light emitting element are flip-chip bonded with its  
11          electrode faced down, and the electrodes are extended to a  
12          surface opposite to the light emission surface of the LED lamp  
13          while being embedded in the package.
- 1           2. The LED lamp according to claim 1, wherein:  
2           the red light emitting element is a plurality of red light  
3           emitting elements, and every two of the plurality of red light  
4           emitting elements are connected in series.
- 1           3. The LED lamp according to claim 1, wherein:  
2           the package is of ceramics material.
- 1           4. An LED lamp, comprising:  
2           a circuit board with a wiring pattern formed thereon; and  
3           a package that houses a light emitting element, the  
4           package being mounted on the circuit board;  
5           wherein the package is provided with a terminal that is

6 electrically connected to the wiring pattern by using solder,  
7 and part of the terminal and/or the wiring pattern is provided  
8 with a cutting region that allows the retention of solder to  
9 be flown thereinto.

1 5. The LED lamp according to claim 4, wherein:  
2 the cutting region is formed by cutting off part of a  
3 mounting surface of the package together with part of the  
4 terminal.

1 6. The LED lamp according to claim 4, wherein:  
2 the terminal is part of a conductive film pattern.

1 7. The LED lamp according to claim 4, wherein:  
2 the package is formed by staking a plurality of ceramics  
3 plates and then baking the plates.

1 8. The LED lamp according to claim 4, wherein:  
2 the package is formed by cutting an assembly that a  
3 plurality of packages are integrally formed, and the cutting  
4 region is formed at a cutting face in cutting the assembly.

1 9. A method of making an LED lamp, comprising the steps  
2 of:

3 preparing a first thin plate with an opening, a second  
4 thin plate with a first wiring pattern formed thereon, and a  
5 third thin plate with a second wiring pattern formed thereon;  
6 stacking the first thin plate, the second thin plate and  
7 the third thin plate in this order;

8           baking the stacked first thin plate, the second thin plate  
9   and the third thin plate to provide an assembly integrating the  
10   first to third thin plates;  
11           mounting an LED in the opening and electrically  
12   connecting the first wiring pattern to the LED; and  
13           cutting the assembly in a predetermined pattern.

1           10. The method according to claim 9, wherein:  
2           the second wiring pattern is provided with a recess in  
3   a predetermined shape formed at its part, the cutting step is  
4   conducted by cutting the assembly along the recess to have a  
5   cutting region at part of the second wiring pattern of LED lamp.